



TRANSMITTAL LETTER
(General - Patent Pending)

Docket No.
E0520CIP

Re Application Of: Kashmir S. Sahota, Diana M. Schonauer, Johannes F. Groschopf, Gerd F.C. Marxsen, Steven A. Avanzino

Serial No.
09/749,191

Filing Date
December 26, 2000

Examiner
L. Umez-Eronini

Group Art Unit
1765

Title: "PREVENTION OF PRECIPITATION DEFECTS ON COPPER INTERCONNECTS DURING CMP BY USE OF SOLUTIONS CONTAINING ORGANIC COMPOUNDS WITH SILICA ADSORPTION AND COPPER CORROSION INHIBITING PROPERTIES"

TO THE ASSISTANT COMMISSIONER FOR PATENTS:

Transmitted herewith is:

Statement under 37 CFR 1.97(e) accompanying Information Disclosure Statement
Information Disclosure Statement
Cited Documents (4 documents)
Return Receipt Postcard

RECEIVED
FEB 04 2002
TC

in the above identified application.

- ☒ No additional fee is required.
- ☐ A check in the amount of _____ is attached.
- ☐ The Assistant Commissioner is hereby authorized to charge and credit Deposit Account No. 01-0365 as described below. A duplicate copy of this sheet is enclosed.
- ☐ Charge the amount of _____
- ☒ Credit any overpayment.
- ☒ Charge any additional fee required.

Deborah W. Wenocur
Signature

Dated: December 27, 2001

Deborah W. Wenocur, Reg. No. 40,221
Agent for Applicant
Advanced Micro Devices, Inc., Technology Law Dept.
One AMD Place, M/S 68
P.O. Box 3453
Sunnyvale, CA 94088-3453

I certify that this document and fee is being deposited on Dec. 31/ 2001 with the U.S. Postal Service as first class mail under 37 C.F.R. 1.8 and is addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.

Deborah W. Wenocur
Signature of Person Mailing Correspondence

Deborah W. Wenocur

Typed or Printed Name of Person Mailing Correspondence

CC:

**STATEMENT UNDER 37 CFR 1.97(e) ACCOMPANYING
INFORMATION DISCLOSURE STATEMENT**

Docket No.
E0520CIP

In Reply, Application Of: **Kashmir S. Sahota, Diana M. Schonauer, Johannes F. Groschopf, Gerd F.C. Marxsen, Steven A. Avanzino**

Serial No.
09/749,191

Filing Date
December 26, 2000

Examiner
L. Umez-Eronini

Group Art Unit
1765

Invention: **"PREVENTION OF PRECIPITATION DEFECTS ON COPPER INTERCONNECTS DURING CMP BY
USE OF SOLUTIONS CONTAINING ORGANIC COMPOUNDS WITH SILICA ADSORPTION AND COPPER
CORROSION INHIBITING PROPERTIES"**

TO THE ASSISTANT COMMISSIONER FOR PATENTS:

This is a statement under the provisions of 37 CFR 1.97(e) in the above-identified application.

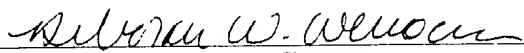
Check applicable statement herebelow:

Statement Under 37 CFR 1.97(e)(1)

- ☒ Each item of information contained in the accompanying Information Disclosure Statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of the Information Disclosure Statement.

Statement Under 37 CFR 1.97(e)(2)

- ☐ No item of information contained in the accompanying Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart foreign application, and, to the knowledge of the undersigned person, after making reasonable inquiry, no item of information contained in the accompanying Information Disclosure Statement was known to any individual designated in 37 CFR 1.56(c) more than three months prior to the filing of the Information Disclosure Statement.

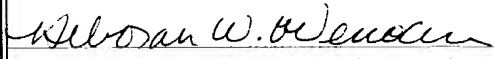

Signature

Dated: December 26, 2001

Deborah W. Wenocur, Reg. No. 40,221
Agent for Applicant
Advanced Micro Devices, Inc., Technology Law Dept.
One AMD Place, M/S 68
P.O. Box 3453
Sunnyvale, CA 94088-3453

Certificate of Mailing by First Class Mail

I certify that this document is being deposited on
December 31, 2001 with the U.S. Postal Service as first
class mail under 37 C.F.R. 1.8 and is addressed to the
Assistant Commissioner for Patents, Washington, D.C.
20231.


Signature of Person Mailing Correspondence

Deborah W. Wenocur

Typed or Printed Name of Person Mailing Correspondence

cc: